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(54) Title (EN): MICROELECTRONIC DEVICE PACKAGE HAVING ALTERNATELY STACKED DIE

(54) Title (FR): BOÎTIER DE DISPOSITIF MICROÉLECTRONIQUE AYANT UNE PUCE EMPILÉE EN ALTERNANCE

(57) Abstract:

(EN): A microelectronic device package including multiple layers of stacked die. Multiple die layers in the package can include two or more die. At least two die in a first layer will be laterally spaced from one another to define a first gap extending in a first direction; and at least two die in a second layer will be laterally spaced from one another to define a second gap extending in a second direction that is angularly offset from the first direction. The first and second directions can be perpendicular to one another.

(FR): L'invention concerne un boîtier de dispositif microélectronique comprenant de multiples couches de puces empilées. De multiples couches de puce dans le boîtier peuvent comprendre deux puces ou plus. Au moins deux puces dans une première couche seront espacées latéralement l'une de l'autre pour définir un premier espace s'étendant dans une première direction; et au moins deux puces dans une seconde couche seront latéralement espacées les unes des autres pour définir un second espace s'étendant dans une seconde direction qui est décalée angulairement par rapport à la première direction. Les première et seconde directions peuvent être perpendiculaires l'une à l'autre.

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